



US00D365584S

United States Patent [19]

[11] Patent Number: **Des. 365,584**

Nakagome et al.

[45] Date of Patent: ****Dec. 26, 1995**

[54] **SEMICONDUCTOR MANUFACTURING DEVICE**

[75] Inventors: **Tatsuya Nakagome; Takashi Tozawa,**
both of Nirasaki, Japan

[73] Assignees: **Tokyo Electron Kabushiki Kaisha,**
Tokyo; **Tokyo Electron Yamanashi Kabushiki Kaisha,**
Nirasaki, both of Japan

[**] Term: **14 Years**

[21] Appl. No.: **24,005**

[22] Filed: **Jun. 6, 1994**

[30] **Foreign Application Priority Data**

Dec. 15, 1993 [JP] Japan 5-37970

[52] U.S. Cl. **D15/199; D10/46; D10/75**

[58] Field of Search D10/46, 75; D15/199;
29/25.01, 33 R, 722, 855; 55/385.2; 156/643,
646, 653, 656; 228/4.5, 175; 257/288, 690,
730, 786; 414/217, 225, 935-941; 437/180-187,
189, 196, 203, 204, 205, 209, 902; 454/182,
851

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 352,911	11/1994	Yamamoto et al.	D10/46 X
4,915,564	4/1990	Eror et al.	414/936 X
5,254,170	10/1993	Devilbiss et al.	414/937 X
5,281,320	1/1994	Turner et al.	414/217 X

Primary Examiner—Antoine Duval Davis
Attorney, Agent, or Firm—Ladas & Parry

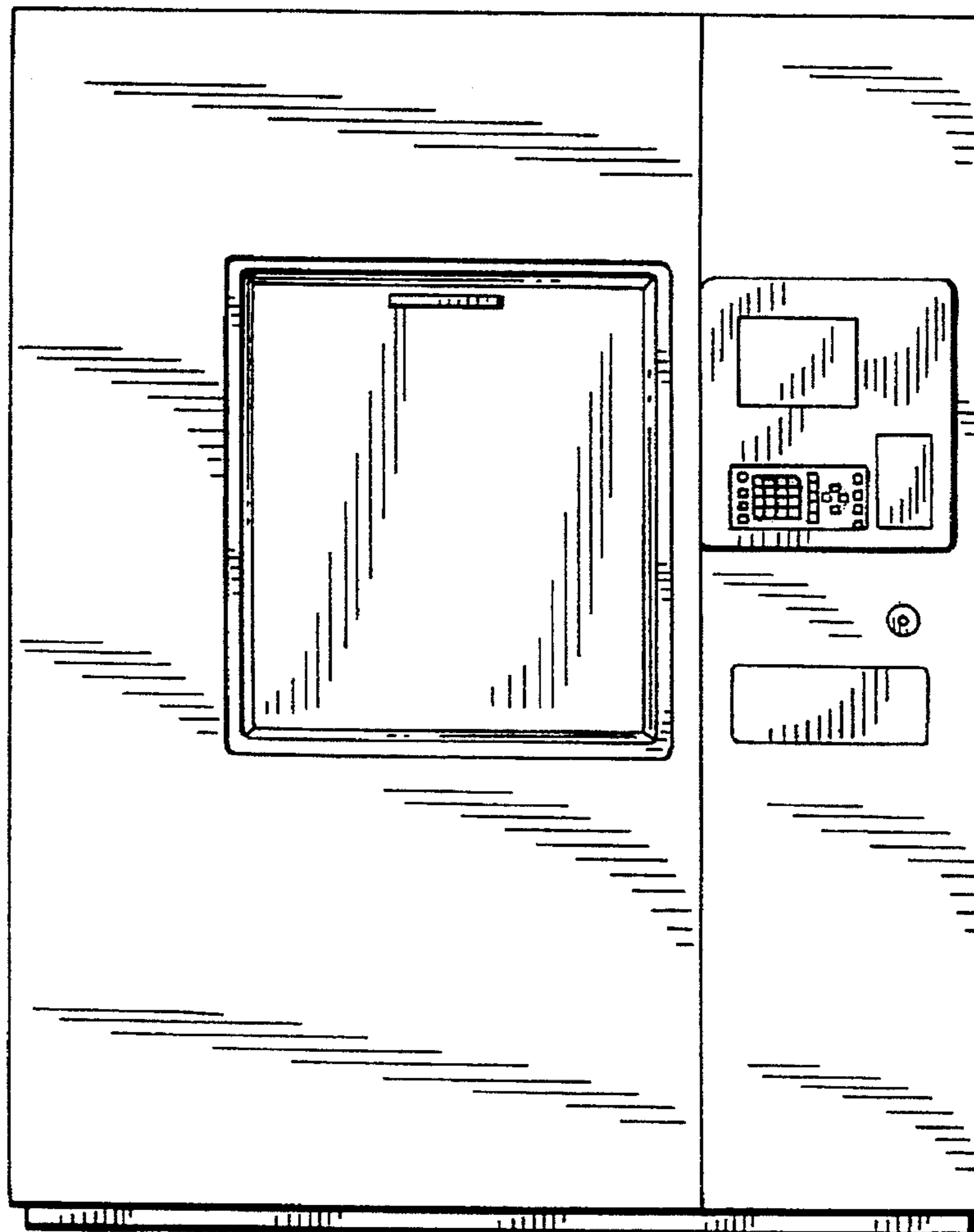
[57] **CLAIM**

The ornamental design for a semiconductor manufacturing device, as shown.

DESCRIPTION

FIG. 1 is a front view of a semiconductor manufacturing device showing my new design; FIG. 2 is a rear view thereof; FIG. 3 is a right side view thereof; FIG. 4 is a left side view thereof; FIG. 5 is a top view thereof; and, FIG. 6 is a bottom view thereof.

1 Claim, 4 Drawing Sheets



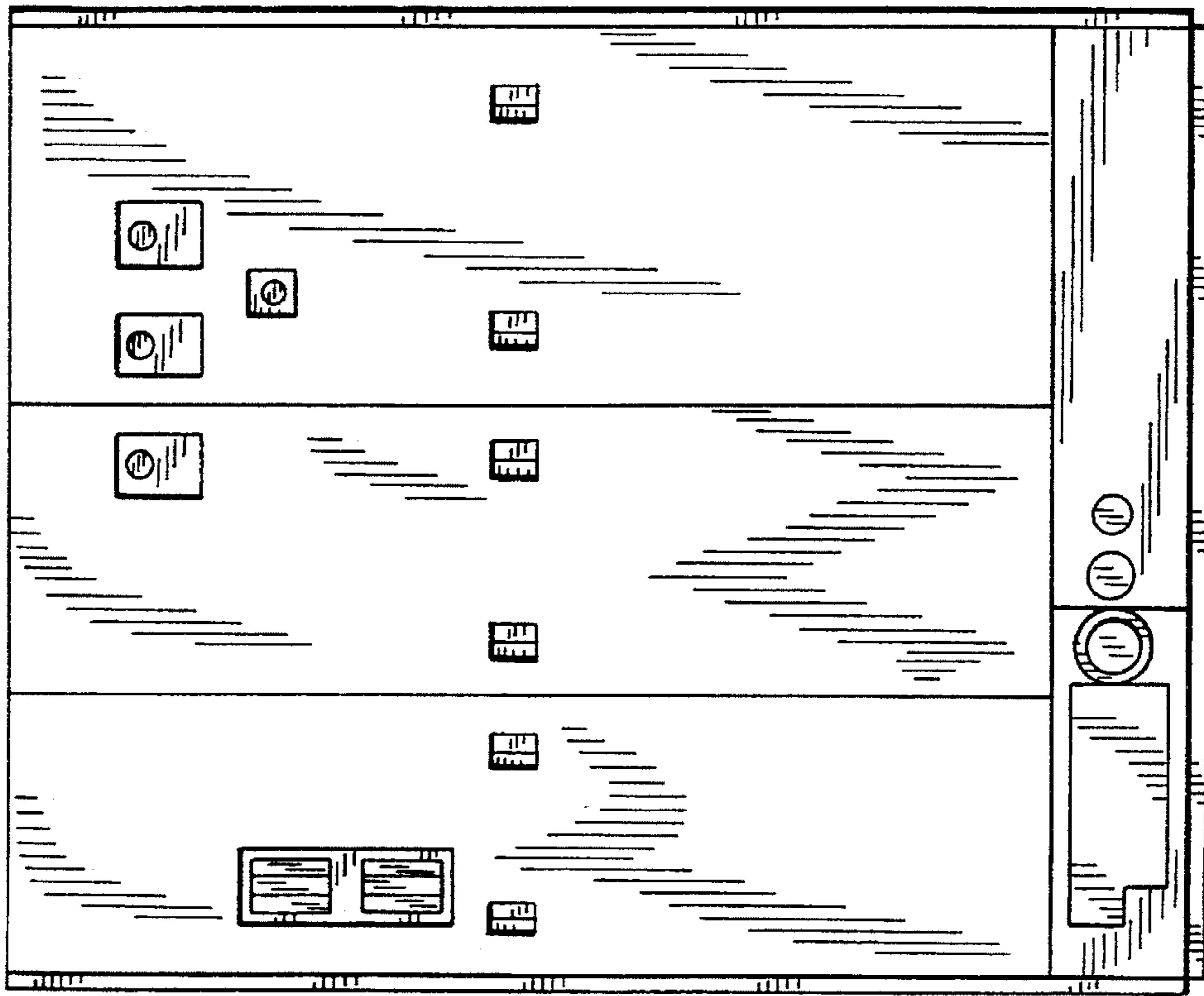


FIG. 2

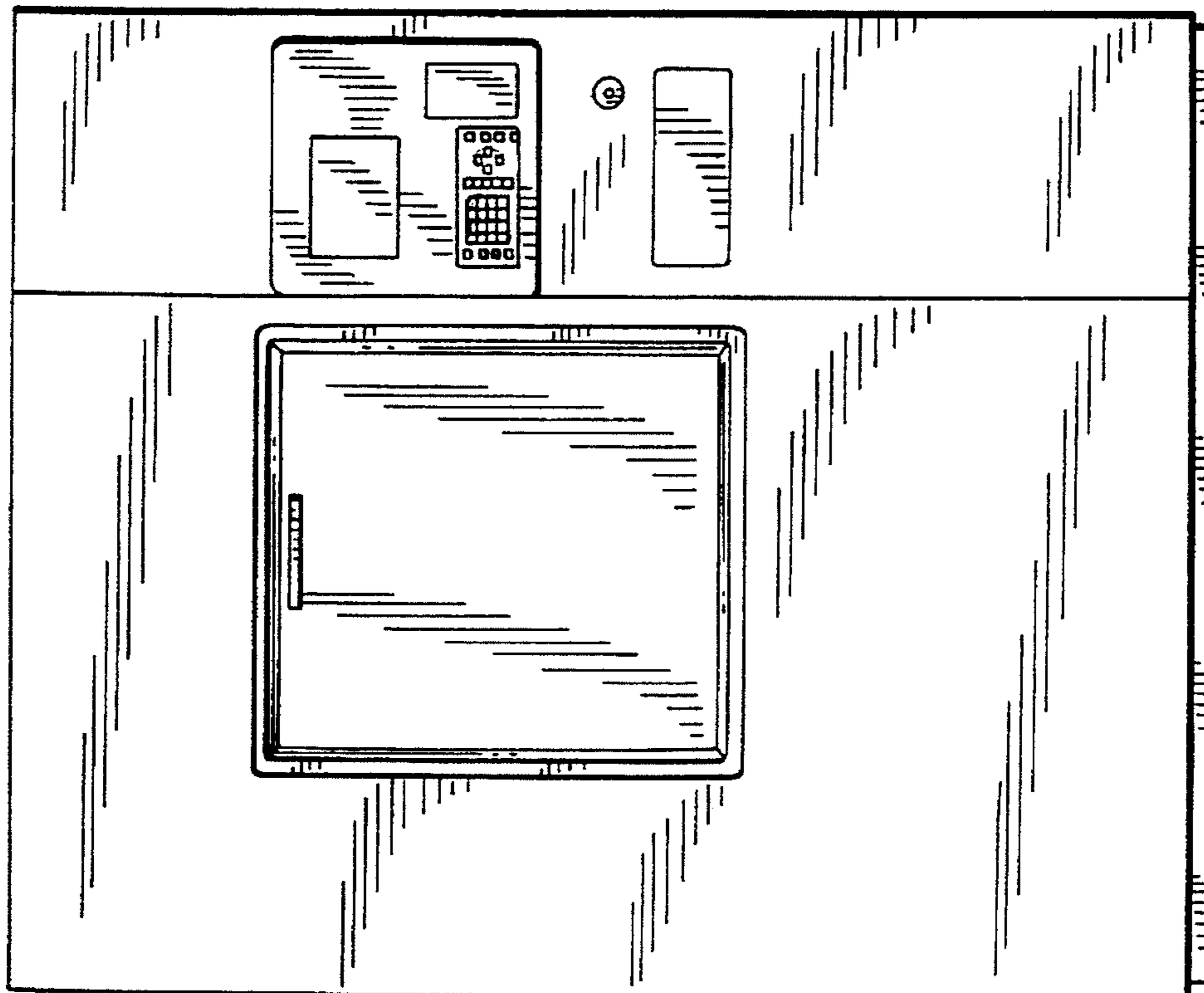


FIG. 1

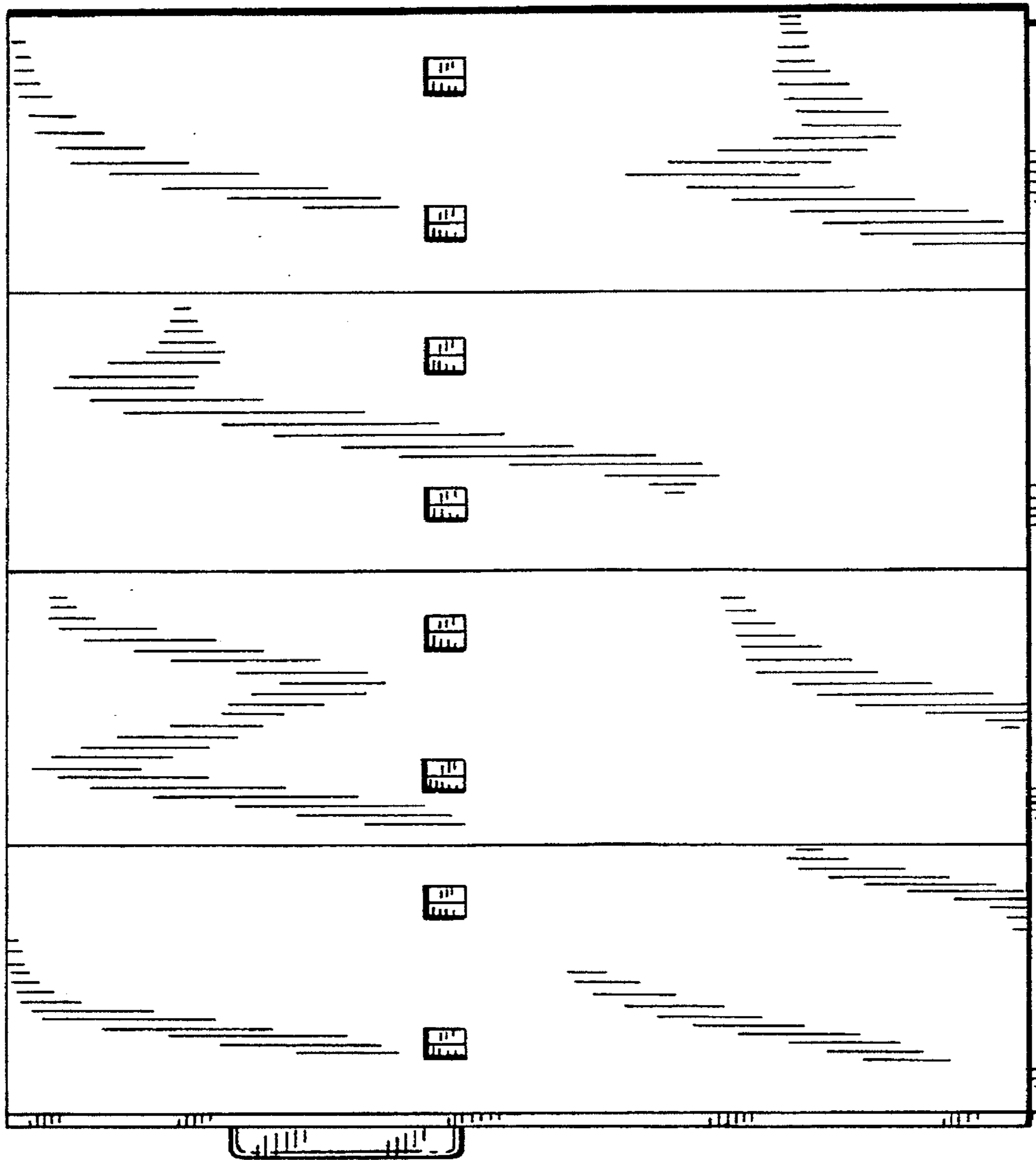


FIG. 3

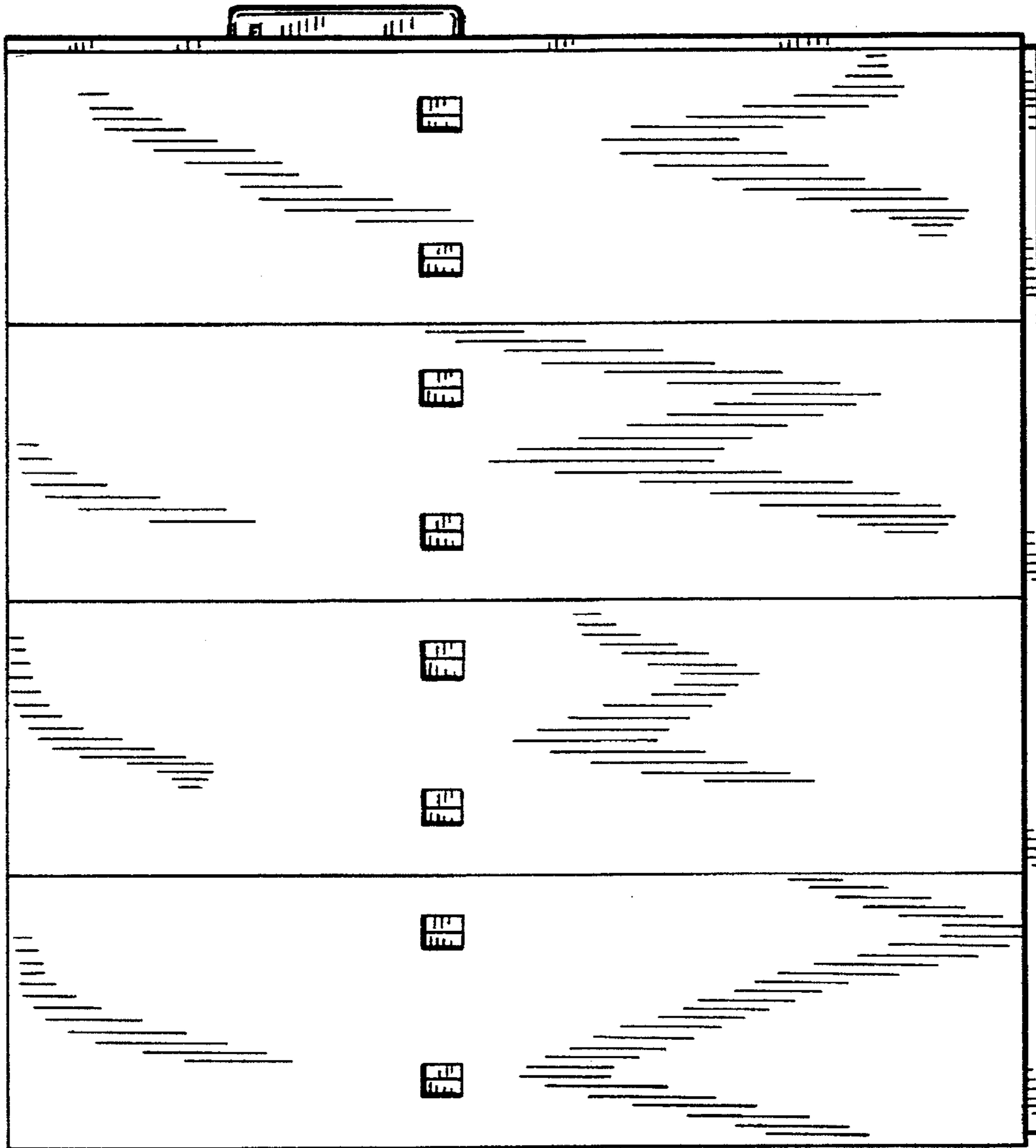


FIG. 4

FIG. 6

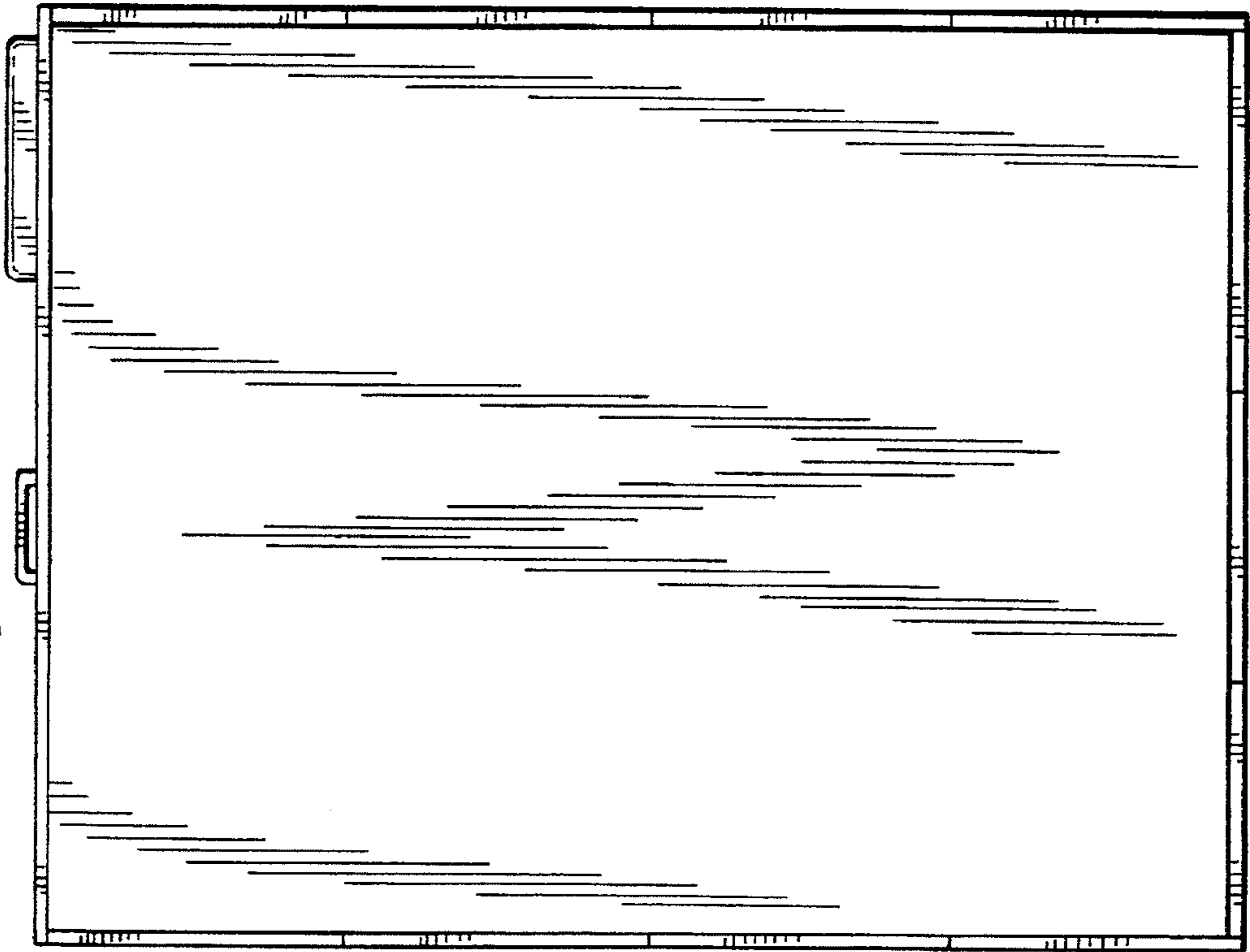


FIG. 5

